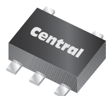
Material Composition Specification

SOT-953 Case



Device average mass . . . . 0.92 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.07%	0.019	Si	7440-21-3	2.07%	0.019	20,661
bond wire	gold	2.07%	0.019	Au	7440-57-5	2.07%	0.019	20,661
leadframe	Cu alloy	27.42%	0.2522	Cu	7440-50-8	26.86%	0.247	268,595
				Fe	7439-89-6	0.54%	0.005	5,437
				P	7723-14-0	0.01%	0.0001	109
				Zn	7440-66-6	0.01%	0.0001	109
die attach	silver epoxy	1.09%	0.01	Ag	7440-22-4	0.98%	0.009	9,787
				resin filler	Proprietary	0.11%	0.001	1,087
encapsulation	EMC	66.44%	0.611	amorphous silica	7631-86-9	64.38%	0.592	643,758
				epoxy resin	Proprietary	1.96%	0.018	19,574
				carbon	1333-86-4	0.11%	0.001	1,087
plating	Ni/Pd/Au	0.91%	0.0084	Ni	7440-02-0	0.87%	0.008	8,699
				Pd	7440-05-3	0.01%	0.0001	109
				Au	7440-57-5	0.03%	0.0003	326

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)